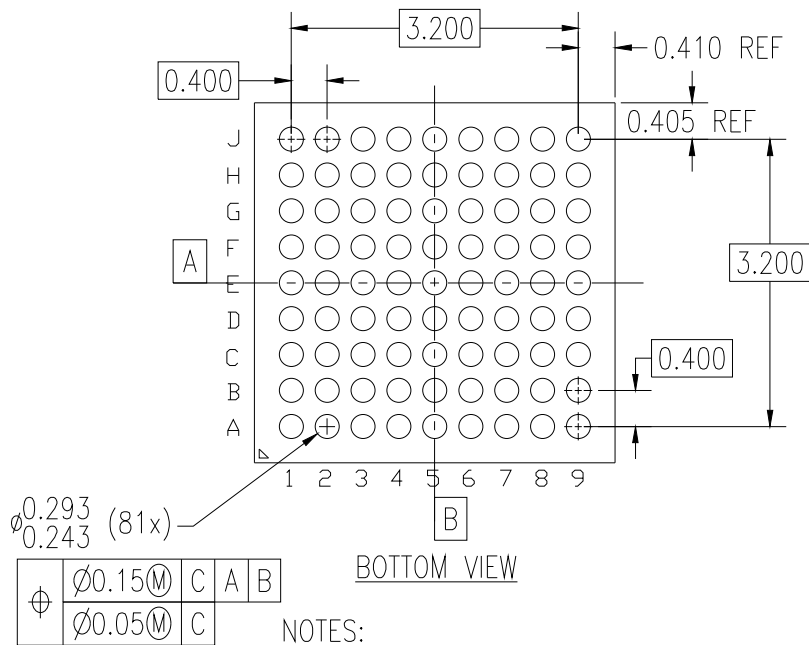
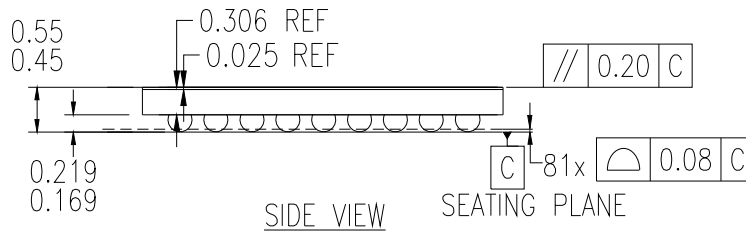
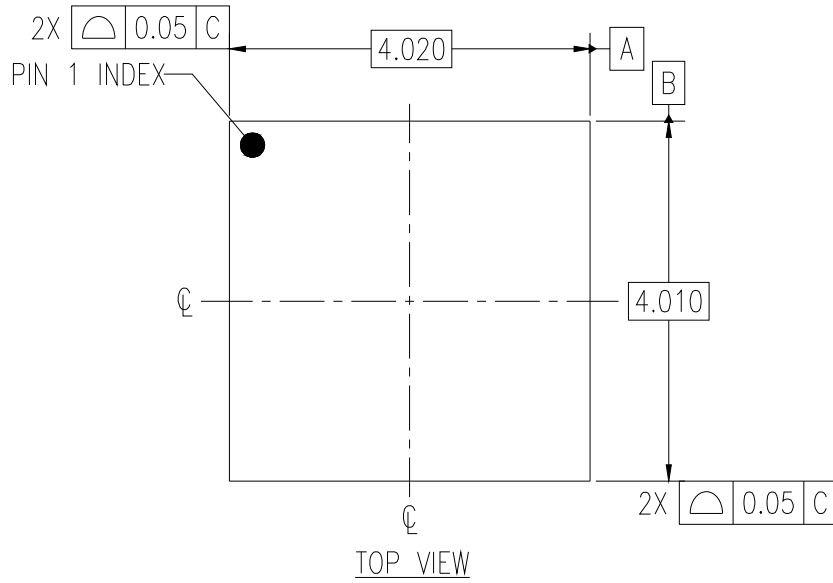


81-DSBGA, Package Outline Drawing

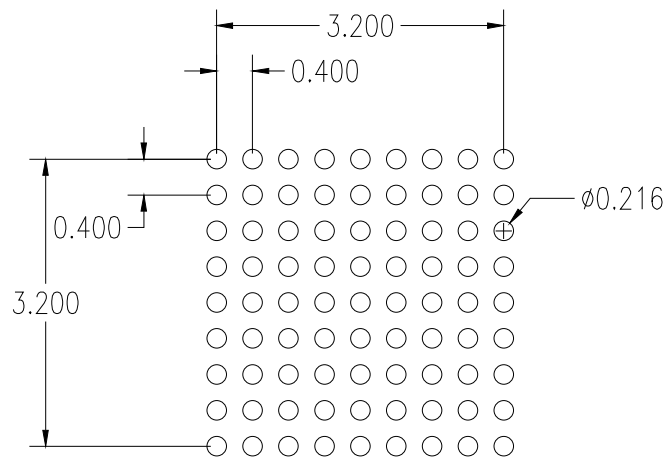
4.02 x 4.01 x 0.5 mm Body, 0.4mm Pitch

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NOTES:

1. ALL DIMENSION ARE IN MM. ANGLES IN DEGREES.
2. DIE STEP SIZE 4.06 x 4.05 MM.



RECOMMENDED LAND PATTERN DIMENSION

NOTE:

1. ALL DIMENSIONS ARE IN MM, ANGLES IN DEGREES.
2. TOP DOWN VIEW, AS VIEW ON PCB.
3. NSMD LAND PATTERN ASSUMED.
4. LAND PATTERN RECOMMENDATION AS PER IDT DSBGA APPLICATION NOTE.

| Package Revision History | | |
|--------------------------|---------|-------------------------------------|
| Date Created | Rev No. | Description |
| March 10, 2020 | Rev 01 | Add Dimension on edge of solderball |
| April 1, 2019 | Rev 00 | Initial Release |